

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	33	(carrier or package or holder or support or socket) near5 (lid or cover) near2 (recessed or recess) and (chip or ic or die) near3 (carrier or package or holder or support or socket) and (test or testing or probe or probing or temporary) near3 (carrier or package or holder or support or socket)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 12:35
L4	11	("4661886").URPN.	USPAT	OR	ON	2005/02/17 12:32
L6	20	(carrier or package or holder or support or socket) near5 (lid or cover) near2 (recessed or recess) near15 (adhesive or glue)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 12:40
L7	30	(carrier or package or holder or support or socket) near5 (lid or cover) near2 (recessed or recess) and (low or short or small or reduced) near (height or profile)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 13:05
L8	459	(carrier or package or holder or support or socket) near3 (standard near wafer or wafer near form)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 16:12
L9	75	(carrier or package or holder or support or socket) near3 (wafer) near5 ((singulated or diced or cleaved) near2 (chip or die or ic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 16:28
L10	4106	(carrier or package or holder or support or socket) and (cover or lid) near2 (magnet or magnetic or ferromagnetic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 16:29
L11	8	(carrier or package or holder or support or socket) near6 (cover or lid) near2 (magnet or magnetic or ferromagnetic) same (ic or chip or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 16:29
L12	17	(carrier or package or holder or support or socket) near8 (cover or lid) near3 (magnet or magnetic or ferromagnetic) same (ic or chip or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 16:31
L13	241	(carrier or package or holder or support or socket) same (cover or lid) near3 ((magnet or magnetic or ferromagnetic) near2 (material or made))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 16:31
S1	10481	(wafer or die or chip or substrate) near3 (carrier or holder or support or package or mounting) same (magnet or ferrous or magnetic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 12:21
S2	4523	(wafer or die or chip or substrate or ic or integrated adj circuit) near3 (carrier or holder or support or package or mounting) near10 (magnet or ferrous or magnetic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:40
S3	2072	(wafer or die or chip or substrate or ic or integrated adj circuit) near3 (carrier or holder or support or package or mounting) near10 (magnet or ferrous or magnetic) near5 (holder or holding or cover or covering or mounting or mounted or secure or secured or securing or adhesive or adhering)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:42

S4	646	(wafer or die or chip or substrate or ic or integrated adj circuit) near3 (carrier or holder or support or package) near10 (magnet or ferrous or magnetic) near4 (held or holding or cover or covering or mounting or mounted or secure or secured or securing or adhesive or adhering)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:42
S5	636	(wafer or die or chip or substrate or ic or integrated adj circuit) near3 (carrier or holder or support or package or chuck) near10 (magnet or ferrous or magnetic or magnetically) near2 (held or holding or cover or covering or mounting or mounted or secure or secured or securing or adhesive or adhering or fastened or fastening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:56
S6	149	(wafer or die or chip or substrate or ic or integrated adj circuit) near3 (carrier or holder or support or package or chuck) and (carrier or holder or support or package or chuck) near6 (indent or indentation or indented or groove or grooved or depression or depressed or recess or recessed) near5 (magnet or ferrous or magnetic or magnetically)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:51
S7	707	(wafer or die or chip or substrate or ic or integrated adj circuit) near3 (carrier or holder or support or package or chuck) and (carrier or holder or support or package or chuck) near4 (magnet or ferrous or magnetic or magnetically) near2 (held or holding or cover or covering or mounting or mounted or secure or secured or securing or adhesive or adhering or fastened or fastening or affix or affixed or affixing or seal or sealed or sealing or bound or bonded)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:57
S8	29	(wafer or die or chip or substrate or ic or integrated adj circuit) near3 (carrier or holder or support or package or chuck) and (carrier or holder or support or package or chuck) near5 (magnet or ferrous or magnetic or magnetically) near2 (held or holding or mounting or mounted or secure or secured or securing or adhesive or adhering or fastened or fastening or affix or affixed or affixing or seal or sealed or sealing or bound or bonded) near5 (cap or cover or capping or covering or seal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:58
S9	1457	(wafer or die or chip or substrate or ic or integrated adj circuit) near3 (carrier or holder or support or package or chuck) near2 (magnet or magnetic or magnetically or ferrous)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:59
S10	489	(wafer or die or chip or substrate or ic or integrated adj circuit) near3 (carrier or holder or support or package or chuck) near2 (magnet or magnetic or magnetically or ferrous) near4 (fasten\$3 or bound or binding or affix\$3 or hold\$3 or held or seal\$3 or adher\$3 or lock\$3 or bind or mount\$3 or secured or securing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 16:24
S11	5	("5986459").URPN.	USPAT	OR	ON	2005/01/28 15:35
S12	3	("5204616"   "5757199"   "5828224").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/28 15:38
S13	11	("4661886").URPN.	USPAT	OR	ON	2005/01/28 15:59
S14	2	("4012723"   "4295181").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/28 16:01
S15	22	(wafer or die or chip or substrate or ic or integrated adj circuit) near3 (carrier or holder or support or package or chuck or support) same (magnet or magnetic or magnetically or ferrous) near (clamp or clamping)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 16:19
S16	402	(wafer or die or chip or substrate or ic or integrated adj circuit) near18 (carrier or holder or support or package or chuck) near10 ((magnet or magnetic or magnetically or ferrous) near (fasten\$3 or bound or binding or affix\$3 or hold\$3 or held or seal\$3 or adher\$3 or lock\$3 or bind or mount\$3 or secured or securing))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 16:25

S17	403	(wafer or die or chip or substrate or ic or integrated adj circuit) near5 (carrier or holder or support or package or chuck or support or plate or base) near10 ((magnet or magnetic or magnetically or ferrous) near (fasten\$3 or bound or binding or affix\$3 or hold\$3 or held or seal\$3 or adher\$3 or lock\$3 or bind or mount\$3 or secured or securing))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 16:33
S18	1	(low near profile) near5 (carrier or holder or support or package or chuck or support or plate or base) near10 ((magnet or magnetic or magnetically or ferrous or electrostatic or electrostatically) near (fasten\$3 or bound or binding or affix\$3 or hold\$3 or held or seal\$3 or adher\$3 or lock\$3 or bind or mount\$3 or secured or securing))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 16:34
S19	71	(low near profile) near5 (carrier or holder or support or package or chuck or support or plate or base) and ((magnet or magnetic or magnetically or ferrous or electrostatic or electrostatically) near (fasten\$3 or bound or binding or affix\$3 or hold\$3 or held or seal\$3 or adher\$3 or lock\$3 or bind or mount\$3 or secured or securing or clamp\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 16:34
S20	11083	(wafer or die or chip or substrate or integrated adj circuit or ic) near6 (carrier or holder or support or package or mounting) near4 (test or probe or testing or temporary)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 10:18
S21	88	(wafer or die or chip or substrate or integrated adj circuit or ic) near3 (carrier or holder or support or package or mounting) near3 (test or probe or testing or temporary) and (lid or cover or holder or seal or ring or binding or binder) near10 (magnet or magnetic or ferromagnet or ferrous or ferride or electromagnet\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 10:34
S22	91	(wafer or die or chip or substrate or integrated adj circuit or ic) near3 (carrier or holder or support or package or mounting or chuck) near3 (test or probe or testing or temporary) and (lid or cover or holder or seal or ring or binding or binder) near10 (magnet or magnetic or ferromagnet or ferrous or ferride or electromagnet\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 11:33
S23	3	("5204616"   "5757199"   "5828224").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/01 10:49
S24	5	("5986459").URPN.	USPAT	OR	ON	2005/02/01 10:49
S25	11	("5247248").URPN.	USPAT	OR	ON	2005/02/01 11:00
S26	11	("4661886").URPN.	USPAT	OR	ON	2005/02/01 11:04
S27	2	("4012723"   "4295181").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/01 11:08
S28	266	(wafer or die or chip or substrate or integrated adj circuit or ic or semiconductor or silicon) near3 (carrier or holder or support or package or mounting or chuck or module or packaging or housing) and (carrier or holder or support or package or packaging or mounting or chuck or module or housing) near8 (lid or cover) near3 (magnet or magnetic or magnetically or ferromagnetically or ferromagnet or ferrous or ferride or electromagnet\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 11:33
S29	641	(electronics or device) near3 (carrier or holder or support or package or mounting or chuck or module or packaging or housing) and (carrier or holder or support or package or packaging or mounting or chuck or module or housing) near8 (lid or cover) near3 (magnet or magnetic or magnetically or ferromagnetically or ferromagnet or ferrous or ferride or electromagnet\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 11:38
S30	124	(electronics or device) near3 (carrier or holder or support or package or mounting or chuck) near3 (test or probe or testing or temporary) and (lid or cover or holder or seal or ring or binding or binder) near10 (magnet or magnetic or ferromagnet or ferrous or ferride or electromagnet\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 11:37

S31	156	(electronics or device) near (carrier or holder or support or package or mounting or chuck or module or packaging or housing) and (carrier or holder or support or package or packaging or mounting or chuck or module or housing) near5 (lid or cover) near2 (magnet or magnetic or magnetically or ferromagnetically or ferromagnet or ferrous or ferride or electromagnet\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 12:06
S32	1843	(low or small) near (profile or height) near (carrier or holder or support or package or mounting or chuck or module or packaging or housing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 12:07
S33	478	(low or small) near (profile or height) near (carrier or holder or support or package or mounting or chuck or module or packaging or housing) same (semiconductor or die or wafer or substrate or chip or ic or integrated near circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 12:11
S34	9	(low or small) near (profile or height) near (carrier or holder or support or package or mounting or chuck or module or packaging or housing) same (semiconductor or die or wafer or substrate or chip or ic or integrated near circuit or device or module) near3 (groove or recess or depression or trench or indent or indentation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 12:56
S35	164	(low or small) near (profile or height) near (carrier or holder or support or package or mounting or chuck or module or packaging or housing) and (semiconductor or die or wafer or substrate or chip or ic or integrated near circuit or device or module) near3 (groove or recess or depression or trench or indent or indentation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 13:17
S36	8	(low or small) near (profile or height) near (carrier or holder or support or package or mounting or chuck or module or packaging or housing) and (wafer) near2 (probe or test or testing or tester or probing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 13:22
S37	471	(die or chip or ic or module or integrated near circuit or device or semiconductor or wafer) near2 (carrier or holder or support or package or mounting or chuck or module or packaging or housing or socket) and (wafer or substrate) near (probe or prober or probing or probed) near (test or testing or tester or tested)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 13:29
S38	1	(low or small or reduced or reducing or decreased or decreasing or smaller) near2 (height or depth or thickness or profile) near8 (die or chip or ic or module or integrated near circuit or device or semiconductor or wafer) near2 (carrier or holder or support or package or mounting or chuck or module or packaging or housing or socket) and (wafer or substrate) near (probe or prober or probing or probed) near (test or testing or tester or tested)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 13:25
S39	9	(low or small or reduced or reducing or decreased or decreasing or smaller) near2 (height or depth or thickness or profile) near4 (carrier or holder or support or package or mounting or chuck or module or packaging or housing or socket) and (wafer or substrate) near (probe or prober or probing or probed) near (test or testing or tester or tested)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 13:27
S40	196	(die or chip or ic or module or integrated near circuit or device or semiconductor or wafer) near2 (carrier or holder or support or package or mounting or chuck or module or packaging or housing or socket) and (wafer or substrate) near (probe or prober or probing or probed) near (test or testing or tester or tested) and (cover or lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:23
S41	113	(wafer or round or circular or disc) near2 (form or formed or shaped or shape) near2 (carrier or holder or support or package or mounting or chuck or module or packaging or housing or socket) same (wafer or substrate or die or ic or chip or component) near2 (cleaved or sawed or singulated or singulation or cleaving or cut or diced or dicing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:26

S42	17	(wafer or round or circular or disc) near2 (form or formed or shaped or shape) near2 (carrier or holder or support or package or mounting or chuck or module or packaging or housing or socket) same (wafer or substrate or die or ic or chip or component) near2 (cleaved or sawed or singulated or singulation or cleaving or cut or diced or dicing) and (test or probe or testing or probing or tester or prober or probed or tested) near (wafer or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:35
S43	26	wafer near form near (carrier or holder or support or chuck or package) near6 (ic or die or chip or device)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:39
S44	37	wafer adj probe adj tester	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/01 14:39
S45	180	(low adj profile) near2 (carrier or tray or chuck or support or housing or package or packaging or interposer or holder) same (lid or cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 12:22
S46	12	(low adj profile) near2 (carrier or tray or chuck or support or housing or package or packaging or interposer or holder) same (single or bare or singulated or cleaved or diced) near2 (wafer or die or chip or device or ic or integrated near circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 12:26
S47	4	(low adj profile) near2 (carrier or tray or chuck or support or housing or package or packaging or interposer or holder) near15 (probe or probing or prober or tester or testing or burn-in)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 12:27
S48	7	(low adj profile) near2 (carrier or tray or chuck or support or housing or package or packaging or interposer or holder) same magnet	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 12:28
S49	1433	(carrier or tray or chuck or support or housing or package or packaging or interposer or holder) same (magnet or magnetic) near (top or cover or lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 13:31
S50	53	(device or ic or integrated adj circuit or die or chip or semiconductor or wafer) near3 (carrier or tray or chuck or support or housing or package or packaging or interposer or holder or socket) same (magnet or magnetic) near (top or cover or lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 12:29
S51	8	(US-20040140424-\$ or US-20040187791-\$).did. or (US-5669599-\$ or US-5986459-\$ or US-6119570-\$ or US-6359456-\$ or US-6401330-\$ or US-6632282-\$).did.	US-PGPUB; USPAT	OR	ON	2005/02/04 12:53
S52	802	324/755.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/04 12:53
S53	59	324/755.ccls. and (magnet or magnetic or magnetically or ferromagnet)	US-PGPUB; USPAT	OR	ON	2005/02/04 13:14
S54	34	361/801.ccls. and (magnet or magnetic or magnetically or ferromagnet)	US-PGPUB; USPAT	OR	ON	2005/02/04 13:18
S55	881	257/48.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/04 13:18
S56	497	257/48.ccls. and (carrier or socket or holder or package or wiring adj board or housing or packaging or support or tray or chuck)	US-PGPUB; USPAT	OR	ON	2005/02/04 13:19

S57	63	257/48.ccls. and (carrier or socket or holder or package or wiring adj board or housing or packaging or support or tray or chuck) same (magnet or magnetically or magnetic or ferromagnet or cover or lid)	US-PGPUB; USPAT	OR	ON	2005/02/04 13:30
S58	131	257/727.ccls. and (carrier or socket or holder or package or wiring adj board or housing or packaging or support or tray or chuck) same (magnet or magnetically or magnetic or ferromagnet or cover or lid)	US-PGPUB; USPAT	OR	ON	2005/02/04 13:31
S59	4	(carrier or tray or chuck or support or housing or package or packaging or interposer or holder) same (singulated or single or diced or cleaved or separated) near2 (die or device) same (magnet or magnetic) near3 (top or cover or lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 13:37
S60	836	(carrier or tray or chuck or support or housing or package or packaging or interposer or holder) with (temporar\$3) with (die or device or chip or wafer or ic or integrated adj circuit or element or module or component) with (test or testing or probe or probing or tested or probed or tester or prober)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 13:42
S61	413	(carrier or tray or chuck or support or housing or package or packaging or interposer or holder) near4 (temporar\$3) near4 (die or device or chip or wafer or ic or integrated adj circuit or element or module or component) near8 (test or testing or probe or probing or tested or probed or tester or prober)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 13:39
S62	3	(carrier or tray or chuck or support or housing or package or packaging or interposer or holder) near4 (temporar\$3) near4 (die or device or chip or wafer or ic or integrated adj circuit or element or module or component) near8 (test or testing or probe or probing or tested or probed or tester or prober) and (lid or cover or top or covering or window or clamp or clamping or seal or retainer or retaining or latch or latching or latched) near3 magnet\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 13:41
S63	0	(carrier or tray or chuck or support or housing or package or packaging or interposer or holder) near4 (temporar\$3) near4 (die or device or chip or wafer or ic or integrated adj circuit or element or module or component) near8 (test or testing or probe or probing or tested or probed or tester or prober) same (low or small or reduced or decreased or smaller or reducing) near3 (height or profile)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 13:42
S64	25	(carrier or tray or chuck or support or housing or package or packaging or interposer or holder) with (temporar\$3) with (die or device or chip or wafer or ic or integrated adj circuit or element or module or component) with (test or testing or probe or probing or tested or probed or tester or prober) and (low or small or reduc\$ or decreas\$ or short) near2 (height or profile)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 14:31
S65	145	(carrier or tray or chuck or support or housing or package or packaging or interposer or holder) with (temporar\$3) with (die or device or chip or wafer or ic or integrated adj circuit or element or module or component) and (cover or lid) near3 (recess or recessed or planar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 14:50
S66	6	("4871110"   "5088639"   "5118027"   "5626277"   "5655704"   "5680984").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/04 14:43
S67	9	("5839191").URPN.	USPAT	OR	ON	2005/02/04 14:44
S68	1837	(carrier or tray or chuck or support or housing or package or packaging or interposer or holder) near3 (die or device or chip or wafer or ic or integrated adj circuit or element or module or component) same (cover or lid) near3 (recess or recessed or groove or depression)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 14:52
S69	523	(carrier or tray or chuck or support or housing or package or packaging or interposer or holder) near2 (die or device or chip or wafer or ic or integrated adj circuit) same (cover or lid) near2 (recess or recessed or groove or depression)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 14:52